

## Specifications

Insulation Resistance:	500MΩ min. at 500V DC
Withstanding Voltage:	250V ACrms for 1 minute
Contact Resistance:	100mΩ max. at 10mA / 20mV max.
Current Rating:	0.5A
Voltage Rating:	5.0Vrms
Operating Temp. Range:	-55°C to +85°C
Mating Cycles:	5,000 insertions

## Materials and Finish

Insulator:	LCP, glass filled (UL94V-0)
Contact Plating:	Mating Face - Gold over Nickel
	Solder Tails - SnCu over Nickel



## Part Number (Details)

**FMS006Z - 200 0 - 0**

Series No.

Design No.

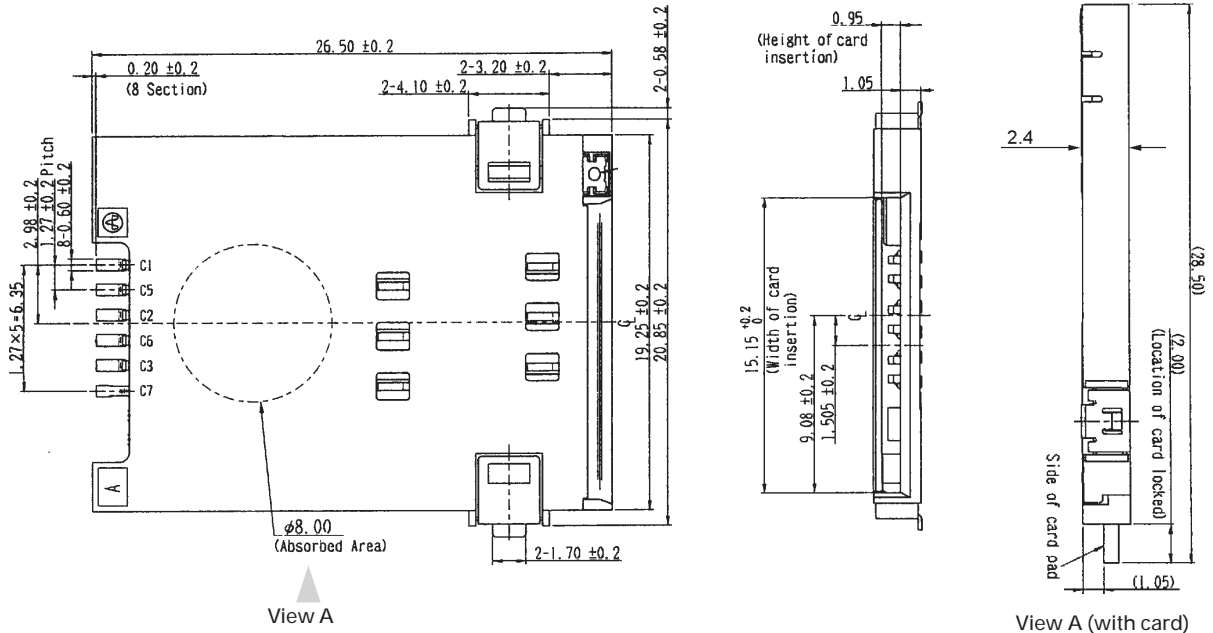
0 = without Switch



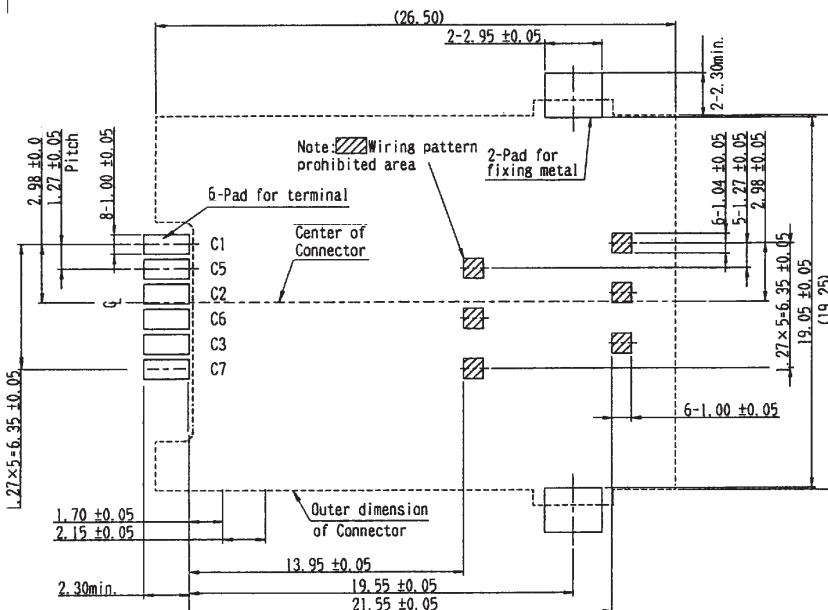
## Features

- ⇨ Conforms to GSM11.11 standard for the European mobile phone system
- ⇨ Smooth extraction function by Push / Push mechanism
- ⇨ Without switch
- ⇨ For assembly on top of the PC-Board
- ⇨ Tape and Reel Packaging (800 pcs./reel)

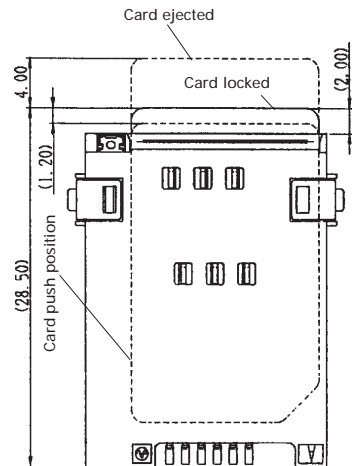
## Outline Connector Dimensions



## Recommended PCB Layout (Mounting Side)



## Card Insertion



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## Part Number (Details)

**FMS006Z - 200 1 - 1**

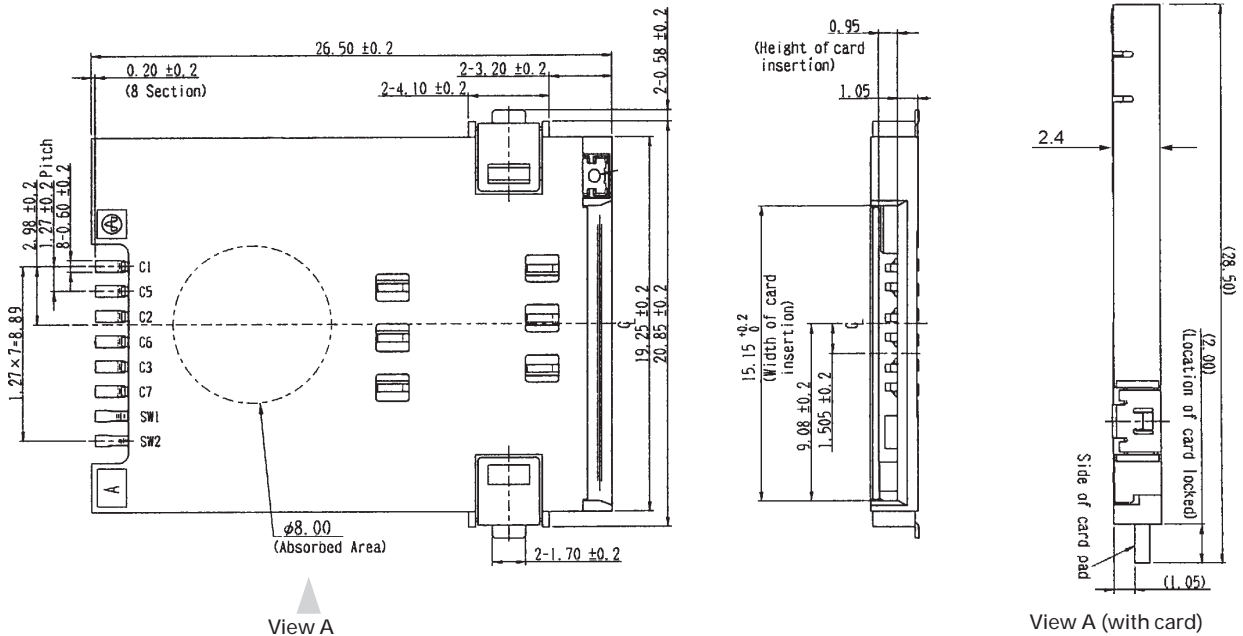
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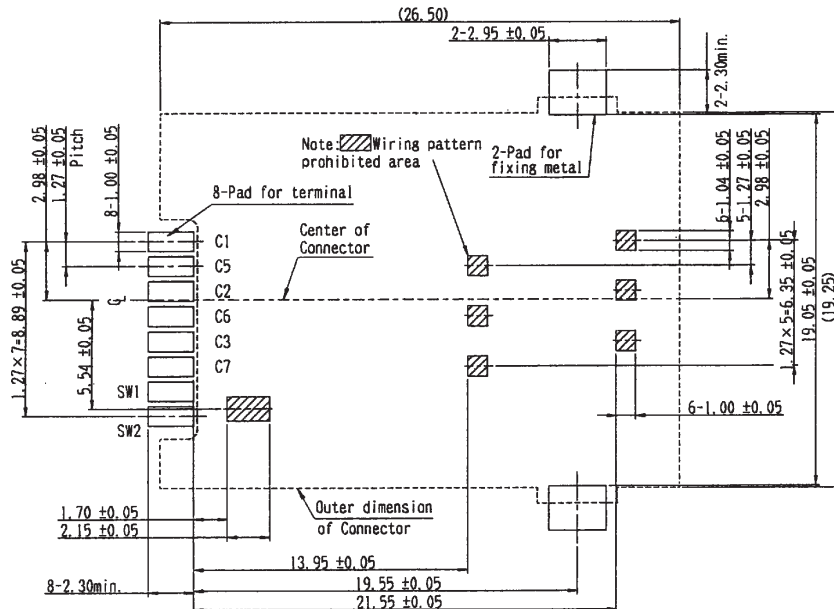
1 = with Switch



## Outline Connector Dimensions



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## Card Insertion

